

# RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	APR '03	31326	0310 NSEB	DJ232810AAB	SOIC	50	50	0
DS1621	A7	JUN '03	31732	0247 ATP (Amkor, PI)	DK104614AA	SOIC	50	50	0

# RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	MAR '03	30969	0237 OSEP	DE106688AAB	SOIC	50	50	0

# RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					CODE	FACILITY	POINT
DS1100	A3	JAN '03	30767	0243	Carsem	DM242094AJC	SOIC	1	4	0
DS1100	A3	APR '03	31251	0312	ATP (Amkor, PI)	DK242100AH	SOIC	1	4	0
DS1100	A3	JUL '03	31896	0323	NSEB	DJ330003ACC	SOIC	1	4	0
DS1232	C2-L	JUL '02	30182	0111	OSEP	DE049638ADB	SOIC	1	4	0
DS1232	C2-L	JAN '03	30755	0252	ATP (Amkor, PI)	DK235629AB	SOIC	1	4	0
DS1232	C2-L	APR '03	31299	0310	Carsem	DM304031AH	SOIC	1	4	0
DS1232	C2-L	JUL '03	31903	0327	ATP (Amkor, PI)	DK343027AA	SOIC	1	4	0
DS1233	A5-5	APR '03	31306	0311	Hana	DU321432DC	SOT223	1	4	0
DS1233	A5-5	JUL '03	31910	0326	Hana	DU338107AK	SOT223	1	4	0
DS1267	A1-5	APR '03	31313	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	5	4	0
DS1621	A7	MAR '03	30963	0237	OSEP	DE106688AAB	SOIC	7	4	0
DS1621	A7	JUN '03	31726	0247	ATP (Amkor, PI)	DK104614AA	SOIC	7	4	0
DS1803	A2	OCT '02	30226	0234	ATP (Amkor, PI)	DK236047AA	SOIC	2	4	0
DS1803	A2	APR '03	31258	0304	OSEP	DE322628AAB	SOIC	2	4	0
DS1803	A2	JUL '03	31925	0317	OSEP	DE335021AAB	SOIC	2	4	0
DS2118M	C1-6	JUN '03	31734	0303	Carsem	DM316629AB	SSOP	6	4	0
DS21352	A4	FEB '03	31026	0242	ATP (Amkor, PI)	DK036653AA	LQFP	2	4	0
DS21352	A4	MAY '03	31398	0312	Stats	DC043465AA	LQFP	2	4	0
DS21Q43	A3-	FEB '03	30955	0305	ATK (Amkor, K)	DN039537AA	LQFP	1	4	0
DS21Q43	A3-	AUG '03	32246	0320	ATK (Amkor, K)	DN041135AA	LQFP	1	4	0
DS2502	C4	APR '03	31265	0310	OSEP	DE311138AM	TSOC	2	4	0
DS2502	C4	JUL '03	31932	0327	OSEP	DE328634AFB	TSOC	2	4	0

## RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	APR '03	31297	0311	Fastech	334654	Module w/Bent Fra	300	100	0
DS12887	A2-	JUL '03	31923	0318	Fastech	335549	Module w/Bent Fra	300	100	0
DS1990	A,F(	MAY '03	31396	0304	Fastech	334377-1	iButton F50w/IC's	500	77	0
DS1992	S-Z(	JUN '03	31653	0315	Fastech	335226-1	iButton F50 w/Bum	500	77	0
DS1992	S-Z(	SEP '03	32403	0332	Fastech	MA336936AA	iButton F50 w/Bum	500	77	0
DS29020	A7-3	JUN '03	31645	0317	Consonic T	DX327020AAA	Cartridge	300	77	0
DS3832	B-C	+ DS3802	30849	0215	Dallas	964558-1	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	30849	0215	Dallas	964558-1	BGA Module, 1 Sid	1000	8	0
DS3832	B-C	+ DS3802	31659	0318	Dallas	315975	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	31659	0318	Dallas	315975	BGA Module, 1 Sid	1000	8	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	JAN '03	30771	0243	Carsem	DM242094AJC	SOIC	500	40	0
DS1100	A3	JAN '03	30771	0243	Carsem	DM242094AJC	SOIC	1000	40	0
DS1100	A3	APR '03	31255	0312	ATP (Amkor, PI)	DK242100AH	SOIC	500	40	0
DS1100	A3	APR '03	31255	0312	ATP (Amkor, PI)	DK242100AH	SOIC	1000	40	0
DS1100	A3	JUL '03	31900	0323	NSEB	DJ330003ACC	SOIC	500	40	0
DS1232	C2-L	JUL '02	30186	0111	OSEP	DE049638ADB	SOIC	500	40	0
DS1232	C2-L	JUL '02	30186	0111	OSEP	DE049638ADB	SOIC	1000	40	0
DS1232	C2-L	JAN '03	30759	0252	ATP (Amkor, PI)	DK235629AB	SOIC	500	40	0
DS1232	C2-L	JAN '03	30759	0252	ATP (Amkor, PI)	DK235629AB	SOIC	1000	40	0
DS1232	C2-L	APR '03	31303	0310	Carsem	DM304031AH	SOIC	500	40	0
DS1232	C2-L	APR '03	31303	0310	Carsem	DM304031AH	SOIC	1000	40	0
DS1232	C2-L	JUL '03	31907	0327	ATP (Amkor, PI)	DK343027AA	SOIC	500	40	0
DS1232	C2-L	JUL '03	31907	0327	ATP (Amkor, PI)	DK343027AA	SOIC	1000	40	0
DS1233	A5-5	APR '03	31310	0311	Hana	DU321432DC	SOT223	1000	40	0
DS1233	A5-5	JUL '03	31914	0326	Hana	DU338107AK	SOT223	700	40	0
DS1233	A5-5	JUL '03	31914	0326	Hana	DU338107AK	SOT223	1000	40	0
DS1267	A1-5	AUG '02	30200	0237	Carsem	DM234023AF	TSSOP	500	40	0
DS1267	A1-5	AUG '02	30200	0237	Carsem	DM234023AF	TSSOP	1000	40	0
DS1267	A1-5	APR '03	31317	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	500	40	0
DS1267	A1-5	APR '03	31317	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	1000	40	0
DS1302	A4	JUN '03	31641	0321	OSEP	DE117012AA	PDIP	500	45	0
DS1302	A4	JUN '03	31641	0321	OSEP	DE117012AA	PDIP	1000	45	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	APR '03	31324	0310	NSEB	DJ232810AAB	SOIC	500	40	0
DS1620	D1	APR '03	31324	0310	NSEB	DJ232810AAB	SOIC	1000	40	0
DS1621	A7	MAR '03	30967	0237	OSEP	DE106688AAB	SOIC	500	40	0
DS1621	A7	MAR '03	30967	0237	OSEP	DE106688AAB	SOIC	1000	40	0
DS1621	A7	JUN '03	31730	0247	ATP (Amkor, PI)	DK104614AA	SOIC	500	40	0
DS1621	A7	JUN '03	31730	0247	ATP (Amkor, PI)	DK104614AA	SOIC	1000	40	0
DS1803	A2	OCT '02	30230	0234	ATP (Amkor, PI)	DK236047AA	SOIC	500	40	0
DS1803	A2	OCT '02	30230	0234	ATP (Amkor, PI)	DK236047AA	SOIC	1000	40	0
DS1803	A2	APR '03	31262	0304	OSEP	DE322628AAB	SOIC	500	40	0
DS1803	A2	APR '03	31262	0304	OSEP	DE322628AAB	SOIC	1000	40	0
DS2118M	C1-6	JUN '03	31738	0303	Carsem	DM316629AB	SSOP	500	77	0
DS2118M	C1-6	JUN '03	31738	0303	Carsem	DM316629AB	SSOP	1000	77	0
DS21352	A4	FEB '03	31030	0242	ATP (Amkor, PI)	DK036653AA	LQFP	500	80	0
DS21352	A4	FEB '03	31030	0242	ATP (Amkor, PI)	DK036653AA	LQFP	1000	69	0
DS21352	A4	MAY '03	31402	0312	Stats	DC043465AA	LQFP	500	80	0
DS21352	A4	MAY '03	31402	0312	Stats	DC043465AA	LQFP	1000	73	0
DS21Q43	A3-	FEB '03	30959	0305	ATK (Amkor, K)	DN039537AA	LQFP	500	70	0
DS2401	C2	MAY '03	31648	0323	Carsem	DM330002AA	TO92	500	45	0
DS2401	C2	MAY '03	31648	0323	Carsem	DM330002AA	TO92	1000	45	0
DS2401	C2	AUG '03	32238	0331	Hana	DU342603AB	TO92	500	45	0
DS2401	C2	AUG '03	32238	0331	Hana	DU342603AB	TO92	1000	45	0
DS2502	C4	APR '03	31268	0310	OSEP	DE311138AM	TSOC	500	77	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C4	APR '03	31268	0310	OSEP	DE311138AM	TSOC	1000	77	0
DS2502	C4	JUL '03	31935	0327	OSEP	DE328634AFB	TSOC	500	77	0
DS2502	C4	JUL '03	31935	0327	OSEP	DE328634AFB	TSOC	1000	77	0
DS80C320	C5	SEP '03	32414	0323	ATEC	DQ338181AA	PDIP	500	45	0
DS80C320	C5	SEP '03	32414	0323	ATEC	DQ338181AA	PDIP	1000	45	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	FEB '03	31041	0305	Dallas	334458	Module w/Hi Densit	500	77	0
DS1643	C1	FEB '03	31041	0305	Dallas	334458	Module w/Hi Densit	1000	77	0
DS1643	C1	MAY '03	31392	0317	Fastech	335494	Module w/Hi Densit	500	77	0
DS1643	C1	MAY '03	31392	0317	Fastech	335494	Module w/Hi Densit	1000	77	0
DS1643	C1	AUG '03	32244	0333	Fastech	MA337100AA	Module w/Hi Densit	500	77	0
DS1643	C1	AUG '03	32244	0333	Fastech	MA337100AA	Module w/Hi Densit	1000	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	APR '03	31327	0310	NSEB	DJ232810AAB	SOIC	500	50	0
DS1620	D1	APR '03	31327	0310	NSEB	DJ232810AAB	SOIC	1000	50	0
DS1621	A7	MAR '03	30970	0237	OSEP	DE106688AAB	SOIC	500	50	0
DS1621	A7	MAR '03	30970	0237	OSEP	DE106688AAB	SOIC	1000	50	0
DS1621	A7	JUN '03	31733	0247	ATP (Amkor, PI)	DK104614AA	SOIC	500	50	0
DS1621	A7	JUN '03	31733	0247	ATP (Amkor, PI)	DK104614AA	SOIC	1000	50	0

## RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	FEB '03	31040	0305	Dallas	334458	Module w/Hi Densit	500	77	0
DS1643	C1	FEB '03	31040	0305	Dallas	334458	Module w/Hi Densit	1000	77	0
DS1643	C1	MAY '03	31391	0317	Fastech	335494	Module w/Hi Densit	500	77	0
DS1643	C1	MAY '03	31391	0317	Fastech	335494	Module w/Hi Densit	1000	77	0
DS1643	C1	AUG '03	32243	0333	Fastech	MA337100AA	Module w/Hi Densit	500	77	0
DS1990	A,F(	MAY '03	31395	0304	Fastech	334377-1	iButton F50w/IC's	500	77	0
DS1990	A,F(	MAY '03	31395	0304	Fastech	334377-1	iButton F50w/IC's	1000	77	0
DS1992	S-Z(	JUN '03	31652	0315	Fastech	335226-1	iButton F50 w/Bum	500	77	0
DS1992	S-Z(	JUN '03	31652	0315	Fastech	335226-1	iButton F50 w/Bum	1000	77	0
DS1992	S-Z(	SEP '03	32402	0332	Fastech	MA336936AA	iButton F50 w/Bum	500	77	0
DS1992	S-Z(	SEP '03	32402	0332	Fastech	MA336936AA	iButton F50 w/Bum	1000	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS29020	A7-3	JUN '03	31644	0317	Consonic T	DX327020AAA	Cartridge	336	77	0
DS3832	B-C	+ DS3802	30848	0215	Dallas	964558-1	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	30848	0215	Dallas	964558-1	BGA Module, 1 Sid	1000	8	0
DS3832	B-C	+ DS3802	31658	0318	Dallas	315975	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	31658	0318	Dallas	315975	BGA Module, 1 Sid	1000	8	0

# RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: JESD22-B102

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	APR '03	31295	0311 Fastech	334654	Module w/Bent Fra	1	3	0
DS12887	A2-	JUL '03	31921	0318 Fastech	335549	Module w/Bent Fra	1	3	0
DS1643	C1	FEB '03	31038	0305 Dallas	334458	Module w/Hi Densit	5	3	0
DS1643	C1	MAY '03	31389	0317 Fastech	335494	Module w/Hi Densit	5	3	0
DS1643	C1	AUG '03	32241	0333 Fastech	MA337100AA	Module w/Hi Densit	5	3	0

# RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					POINT	QTY	FAIL
DS1100	A3	JAN '03	30769	0243	Carsem	DM242094AJC	SOIC	1	4	0
DS1100	A3	APR '03	31253	0312	ATP (Amkor, PI)	DK242100AH	SOIC	1	4	0
DS1100	A3	JUL '03	31898	0323	NSEB	DJ330003ACC	SOIC	1	4	0
DS1232	C2-L	JUL '02	30184	0111	OSEP	DE049638ADB	SOIC	7	4	0
DS1232	C2-L	JAN '03	30757	0252	ATP (Amkor, PI)	DK235629AB	SOIC	7	4	0
DS1232	C2-L	APR '03	31301	0310	Carsem	DM304031AH	SOIC	7	4	0
DS1232	C2-L	JUL '03	31905	0327	ATP (Amkor, PI)	DK343027AA	SOIC	7	4	0
DS1233	A5-5	APR '03	31308	0311	Hana	DU321432DC	SOT223	2	4	0
DS1233	A5-5	JUL '03	31912	0326	Hana	DU338107AK	SOT223	2	4	0
DS1267	A1-5	APR '03	31315	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	2	4	0
DS1620	D1	APR '03	31322	0310	NSEB	DJ232810AAB	SOIC	7	4	0
DS1621	A7	MAR '03	30965	0237	OSEP	DE106688AAB	SOIC	7	4	0
DS1621	A7	JUN '03	31728	0247	ATP (Amkor, PI)	DK104614AA	SOIC	7	4	0
DS1803	A2	OCT '02	30228	0234	ATP (Amkor, PI)	DK236047AA	SOIC	2	4	0
DS1803	A2	APR '03	31260	0304	OSEP	DE322628AAB	SOIC	2	4	0
DS2118M	C1-6	JUN '03	31736	0303	Carsem	DM316629AB	SSOP	6	4	0
DS21352	A4	FEB '03	31028	0242	ATP (Amkor, PI)	DK036653AA	LQFP	5	4	0
DS21352	A4	MAY '03	31400	0312	Stats	DC043465AA	LQFP	5	4	0
DS21Q43	A3-	FEB '03	30957	0305	ATK (Amkor, K)	DN039537AA	LQFP	1	4	0
DS2502	C4	APR '03	31267	0310	OSEP	DE311138AM	TSOC	2	4	0
DS2502	C4	JUL '03	31934	0327	OSEP	DE328634AFB	TSOC	2	4	0

# RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: JESD22-B100

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	APR '03	31296	0311 Fastech	334654	Module w/Bent Fra	1	6	0
DS12887	A2-	JUL '03	31922	0318 Fastech	335549	Module w/Bent Fra	1	6	0
DS1643	C1	FEB '03	31039	0305 Dallas	334458	Module w/Hi Densit	5	6	0
DS1643	C1	MAY '03	31390	0317 Fastech	335494	Module w/Hi Densit	5	6	0
DS1643	C1	AUG '03	32242	0333 Fastech	MA337100AA	Module w/Hi Densit	5	6	0

## RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	FEB '03	31042	0305	Dallas	334458	Module w/Hi Densit	500	77	0
DS1643	C1	MAY '03	31393	0317	Fastech	335494	Module w/Hi Densit	500	77	0
DS1643	C1	AUG '03	32245	0333	Fastech	MA337100AA	Module w/Hi Densit	500	77	0
DS1990	A,F(	MAY '03	31397	0304	Fastech	334377-1	iButton F50w/IC's	500	77	0
DS1990	A,F(	MAY '03	31397	0304	Fastech	334377-1	iButton F50w/IC's	1000	77	0
DS1992	S-Z(	JUN '03	31654	0315	Fastech	335226-1	iButton F50 w/Bum	500	76	0
DS1992	S-Z(	JUN '03	31654	0315	Fastech	335226-1	iButton F50 w/Bum	1000	76	0
DS1992	S-Z(	SEP '03	32404	0332	Fastech	MA336936AA	iButton F50 w/Bum	500	75	0
DS3832	B-C	+ DS3802	30850	0215	Dallas	964558-1	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	30850	0215	Dallas	964558-1	BGA Module, 1 Sid	1000	8	0
DS3832	B-C	+ DS3802	31660	0318	Dallas	315975	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	31660	0318	Dallas	315975	BGA Module, 1 Sid	1000	8	0

# RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 85 C/85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS29020	A7-3	JUN '03	31646	0317 Consonic T	DX327020AAA	Cartridge	274	77	0

# RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS21352	A4	FEB '03	31031	0242 ATP (Amkor, PI)	DK036653AA	LQFP	96	78	0
DS21352	A4	MAY '03	31403	0312 Stats	DC043465AA	LQFP	96	77	0

# RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	JUL '02	30187	0111 OSEP	DE049638ADB	SOIC	96	77	0
DS1232	C2-L	JAN '03	30760	0252 ATP (Amkor, PI)	DK235629AB	SOIC	96	77	0
DS1232	C2-L	APR '03	31304	0310 Carsem	DM304031AH	SOIC	96	77	0
DS1233	A5-5	APR '03	31311	0311 Hana	DU321432DC	SOT223	96	77	0
DS1233	A5-5	JUL '03	31915	0326 Hana	DU338107AK	SOT223	96	77	0
DS2401	C2	MAY '03	31649	0323 Carsem	DM330002AA	TO92	96	77	0

# RELIABILITY MONITOR

STRESS: EXTERNAL VISUAL

CONDITIONS: JESD22-B101

PRODUCT	REV	MONITOR	DATE	ASSEMBLY	DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	POINT	QTY	FAIL
		DATE	JOB NO	CODE	FACILITY							
DS3832	B-C	+ DS3802	30849	0215	Dallas		964558-1	BGA Module, 1 Sid	6		8	0
DS3832	B-C	+ DS3802	31656	0318	Dallas		315975	BGA Module, 1 Sid	2		24	0

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS3832	B-C	+ DS3802	30846	0215 Dallas	964558-1	BGA Module, 1 Sid	2	24	0
DS3832	B-C	+ DS3802	31656	0318 Dallas	315975	BGA Module, 1 Sid	2	24	0

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE	ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					POINT	QTY	FAIL
DS1100	A3	JAN '03	30768	0243	Carsem	DM242094AJC	SOIC	3	241	0
DS1100	A3	APR '03	31252	0312	ATP (Amkor, PI)	DK242100AH	SOIC	3	241	0
DS1100	A3	JUL '03	31897	0323	NSEB	DJ330003ACC	SOIC	3	241	0
DS1232	C2-L	JUL '02	30183	0111	OSEP	DE049638ADB	SOIC	3	241	0
DS1232	C2-L	JAN '03	30756	0252	ATP (Amkor, PI)	DK235629AB	SOIC	3	241	0
DS1232	C2-L	APR '03	31300	0310	Carsem	DM304031AH	SOIC	3	241	0
DS1232	C2-L	JUL '03	31904	0327	ATP (Amkor, PI)	DK343027AA	SOIC	3	241	0
DS1233	A5-5	APR '03	31307	0311	Hana	DU321432DC	SOT223	3	241	0
DS1233	A5-5	JUL '03	31911	0326	Hana	DU338107AK	SOT223	3	241	0
DS1267	A1-5	AUG '02	30197	0237	Carsem	DM234023AF	TSSOP	3	241	0
DS1267	A1-5	APR '03	31314	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	3	241	0
DS1620	D1	APR '03	31321	0310	NSEB	DJ232810AAB	SOIC	3	244	0
DS1621	A7	MAR '03	30964	0237	OSEP	DE106688AAB	SOIC	3	240	0
DS1621	A7	JUN '03	31727	0247	ATP (Amkor, PI)	DK104614AA	SOIC	3	241	0
DS1621	A7	SEP '03	32321	0326	OSEP	DE319631AAB	SOIC	3	241	0
DS1803	A2	OCT '02	30227	0234	ATP (Amkor, PI)	DK236047AA	SOIC	3	241	0
DS1803	A2	APR '03	31259	0304	OSEP	DE322628AAB	SOIC	3	241	0
DS2118M	C1-6	JUN '03	31735	0303	Carsem	DM316629AB	SSOP	3	238	0
DS21352	A4	FEB '03	31027	0242	ATP (Amkor, PI)	DK036653AA	LQFP	3	241	0
DS21352	A4	MAY '03	31399	0312	Stats	DC043465AA	LQFP	3	241	0
DS21Q43	A3-	FEB '03	30956	0305	ATK (Amkor, K)	DN039537AA	LQFP	3	241	0
DS2502	C4	APR '03	31266	0310	OSEP	DE311138AM	TSOC	3	151	0

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C4	JUL '03	31933	0327 OSEP	DE328634AFB	TSOC	3	151	0

# RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	JAN '03	30772	0243	Carsem	DM242094AJC	SOIC	500	77	0
DS1100	A3	JAN '03	30772	0243	Carsem	DM242094AJC	SOIC	1000	77	0
DS1100	A3	APR '03	31256	0312	ATP (Amkor, PI)	DK242100AH	SOIC	500	77	0
DS1100	A3	APR '03	31256	0312	ATP (Amkor, PI)	DK242100AH	SOIC	1000	77	0
DS1100	A3	JUL '03	31901	0323	NSEB	DJ330003ACC	SOIC	500	77	0
DS1267	A1-5	AUG '02	30201	0237	Carsem	DM234023AF	TSSOP	1000	77	0
DS1267	A1-5	APR '03	31318	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	500	77	0
DS1267	A1-5	APR '03	31318	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	1000	77	0
DS12887	A2-	APR '03	31298	0311	Fastech	334654	Module w/Bent Fra	500	100	0
DS12887	A2-	JUL '03	31924	0318	Fastech	335549	Module w/Bent Fra	1000	99	0
DS1302	A4	JUN '03	31642	0321	OSEP	DE117012AA	PDIP	500	77	0
DS1302	A4	JUN '03	31642	0321	OSEP	DE117012AA	PDIP	1000	77	0
DS1620	D1	APR '03	31325	0310	NSEB	DJ232810AAB	SOIC	500	70	0
DS1620	D1	APR '03	31325	0310	NSEB	DJ232810AAB	SOIC	1000	70	0
DS1621	A7	MAR '03	30968	0237	OSEP	DE106688AAB	SOIC	500	70	0
DS1621	A7	MAR '03	30968	0237	OSEP	DE106688AAB	SOIC	1000	70	0
DS1621	A7	JUN '03	31731	0247	ATP (Amkor, PI)	DK104614AA	SOIC	500	70	0
DS1621	A7	JUN '03	31731	0247	ATP (Amkor, PI)	DK104614AA	SOIC	1000	70	0
DS1803	A2	OCT '02	30231	0234	ATP (Amkor, PI)	DK236047AA	SOIC	500	77	0
DS1803	A2	APR '03	31263	0304	OSEP	DE322628AAB	SOIC	500	77	0
DS1803	A2	APR '03	31263	0304	OSEP	DE322628AAB	SOIC	1000	77	0
DS80C320	C5	SEP '03	32415	0323	ATEC	DQ338181AA	PDIP	500	77	0

# RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	JAN '03	30773	0243	Carsem	DM242094AJC	SOIC	168	40	0
DS1100	A3	APR '03	31257	0312	ATP (Amkor, PI)	DK242100AH	SOIC	168	39	0
DS1100	A3	JUL '03	31902	0323	NSEB	DJ330003ACC	SOIC	168	40	0
DS1232	C2-L	JUL '02	30188	0111	OSEP	DE049638ADB	SOIC	168	40	0
DS1232	C2-L	JAN '03	30761	0252	ATP (Amkor, PI)	DK235629AB	SOIC	168	40	0
DS1232	C2-L	APR '03	31305	0310	Carsem	DM304031AH	SOIC	168	40	0
DS1232	C2-L	JUL '03	31909	0327	ATP (Amkor, PI)	DK343027AA	SOIC	168	40	0
DS1233	A5-5	APR '03	31312	0311	Hana	DU321432DC	SOT223	168	40	0
DS1233	A5-5	JUL '03	31916	0326	Hana	DU338107AK	SOT223	168	40	0
DS1267	A1-5	APR '03	31319	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	168	40	0
DS1302	A4	JUN '03	31643	0321	OSEP	DE117012AA	PDIP	168	45	0
DS1803	A2	OCT '02	30232	0234	ATP (Amkor, PI)	DK236047AA	SOIC	168	40	0
DS1803	A2	APR '03	31264	0304	OSEP	DE322628AAB	SOIC	168	40	0
DS2118M	C1-6	JUN '03	31739	0303	Carsem	DM316629AB	SSOP	168	77	0
DS2401	C2	MAY '03	31650	0323	Carsem	DM330002AA	TO92	168	45	0
DS2401	C2	AUG '03	32240	0331	Hana	DU342603AB	TO92	168	45	0
DS2502	C4	APR '03	31269	0310	OSEP	DE311138AM	TSOC	168	70	0
DS2502	C4	JUL '03	31936	0327	OSEP	DE328634AFB	TSOC	168	70	0

# RELIABILITY MONITOR

STRESS: 0 HR TEST

CONDITIONS: Connect Cap & Base

PRODUCT	REV	MONITOR	DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	QTY	FAIL
		DATE	JOB NO	CODE FACILITY			POINT		
DS3832	B-C	+ DS3802	30847	0215 Dallas	964558-1	BGA Module, 1 Sid	1	24	0
DS3832	B-C	+ DS3802	31657	0318 Dallas	315975	BGA Module, 1 Sid	1	24	0